Plasma Asher

- TePla M4L RF plasma surface modification system is located in the Class-1000 cleanroom.
- Plasma cleaning of organic materials or removal of photo resist by ions energized through a plasma field, chemically dissolve or etch away exposed wafer surfaces.
- The system utilizes a13.56 Mhz RF generator, two 500 sccm mass flow controller with Oxygen and Argon gases.